

	Type	L #	Hits	Search Text	DBs
8	BRS	L7	28	L1 and (resin or seal\$3 or encapsula\$2 or protective or molding) and thickness and (substrate or board or interposer) and wiring and angle and (boundary or periphery)	US-PGPUB; USPAT; USOCR

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1928	257/787.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1262	257/780.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1638	257/784.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	2525	257/778.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	453	257/784.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	10	((chip or die) and (resin or seal\$3 or encapsula\$2 or protective or molding) and thickness and (substrate or board or interposer) and wiring and angle and (boundary or periphery)).clm.	US-PGPUB